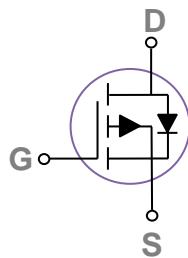


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK3X3 Pin Configuration



BVDSS	RDS(ON)	ID
-20V	8mΩ	-60A

### Features

- -20V, -60A,  $RDS(ON) = 8m\Omega @ VGS = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Networking
- Hand-Held Instruments

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	-60	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	-38	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-240	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	62.5	W
	Power Dissipation – Derate above 25°C	0.5	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.01	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-8\text{A}$	---	6	8	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_{\text{D}}=-5\text{A}$	---	8	11	
		$V_{\text{GS}}=-1.8\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	11	16	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-0.3	-0.6	-1.0	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{S}}=-5\text{A}$	---	20	---	S

**Dynamic and switching Characteristics**

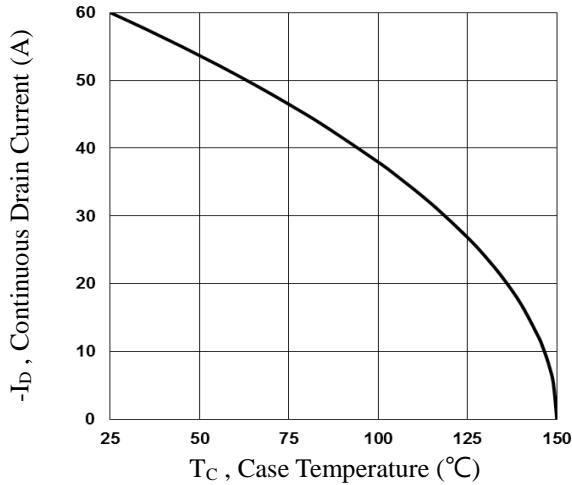
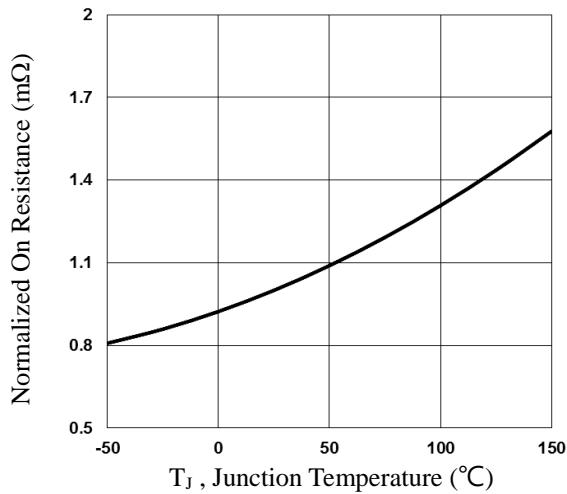
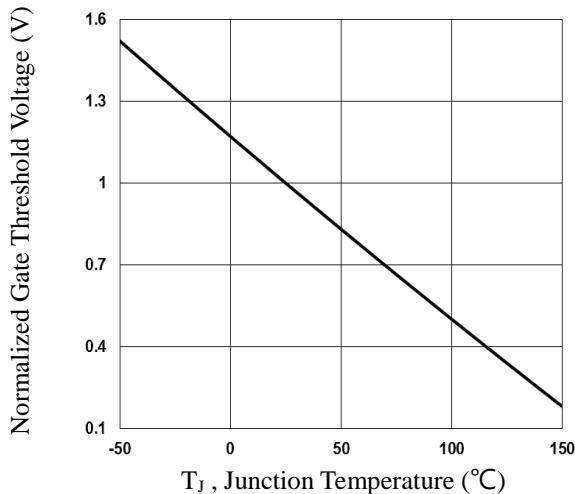
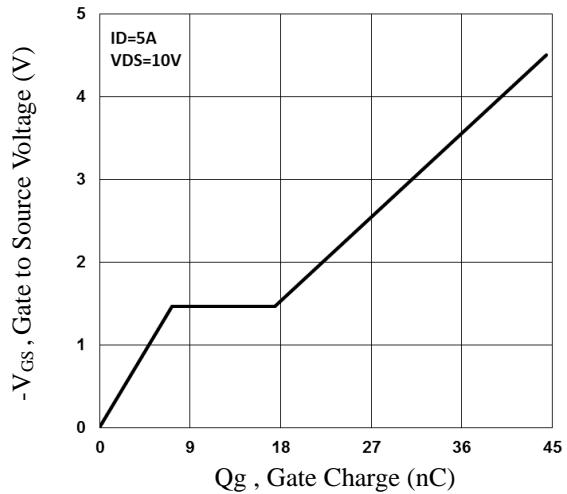
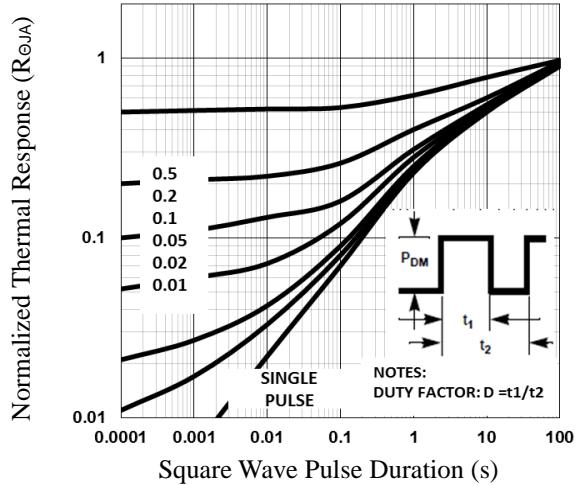
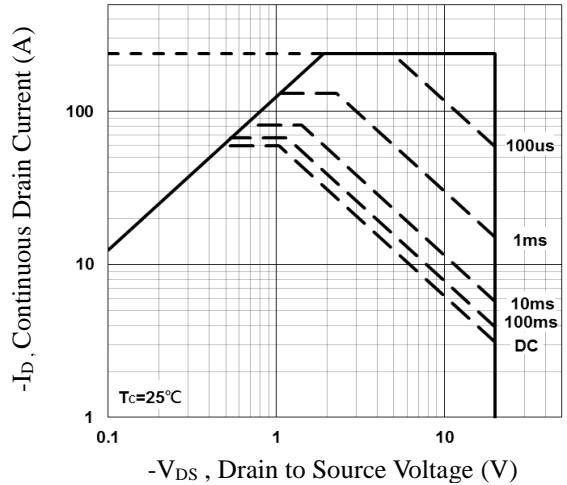
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-5\text{A}$	---	44.4	80	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	7.2	14	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	10.2	20	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=-10\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $R_{\text{G}}=25\Omega$ $I_{\text{D}}=-1\text{A}$	---	13.2	26	nS
$T_r$	Rise Time <sup>2, 3</sup>		---	68	120	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	160	320	
$T_f$	Fall Time <sup>2, 3</sup>		---	154	300	
$C_{\text{iss}}$	Input Capacitance		---	4060	8000	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	520	1000	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	400	800	

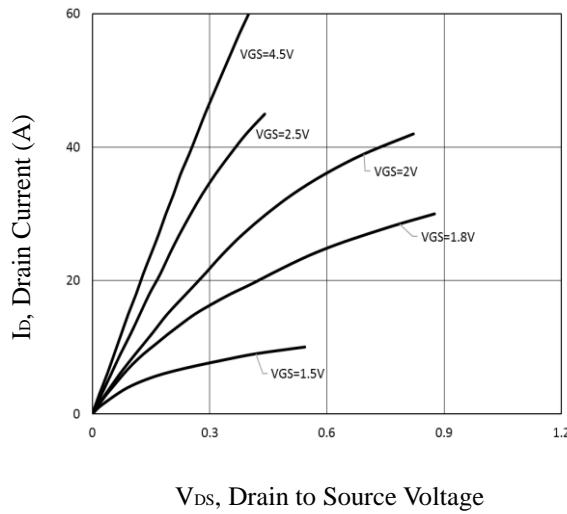
**Drain-Source Diode Characteristics and Maximum Ratings**

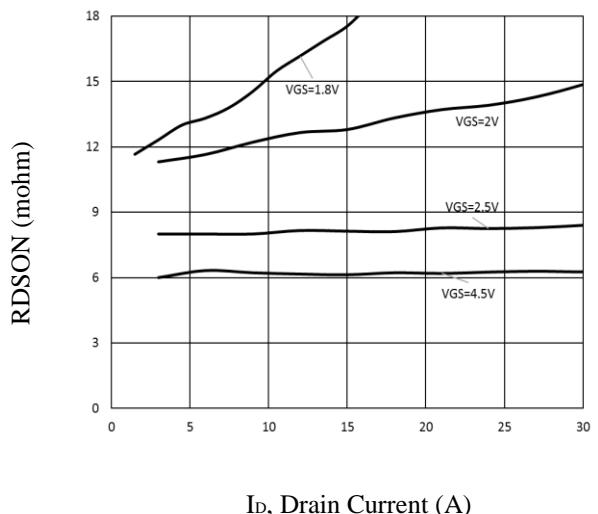
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-60	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	-120	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

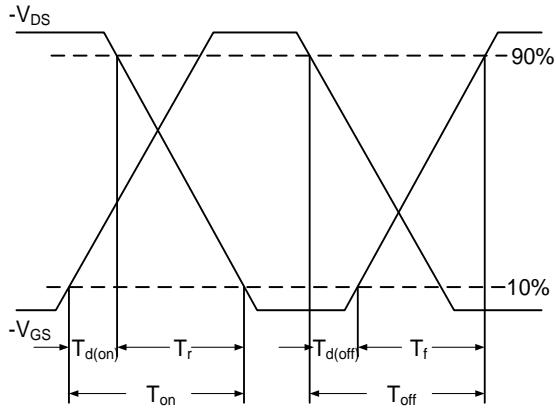
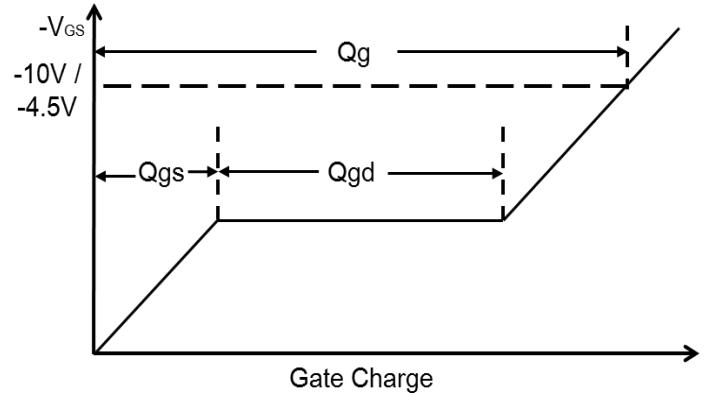
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

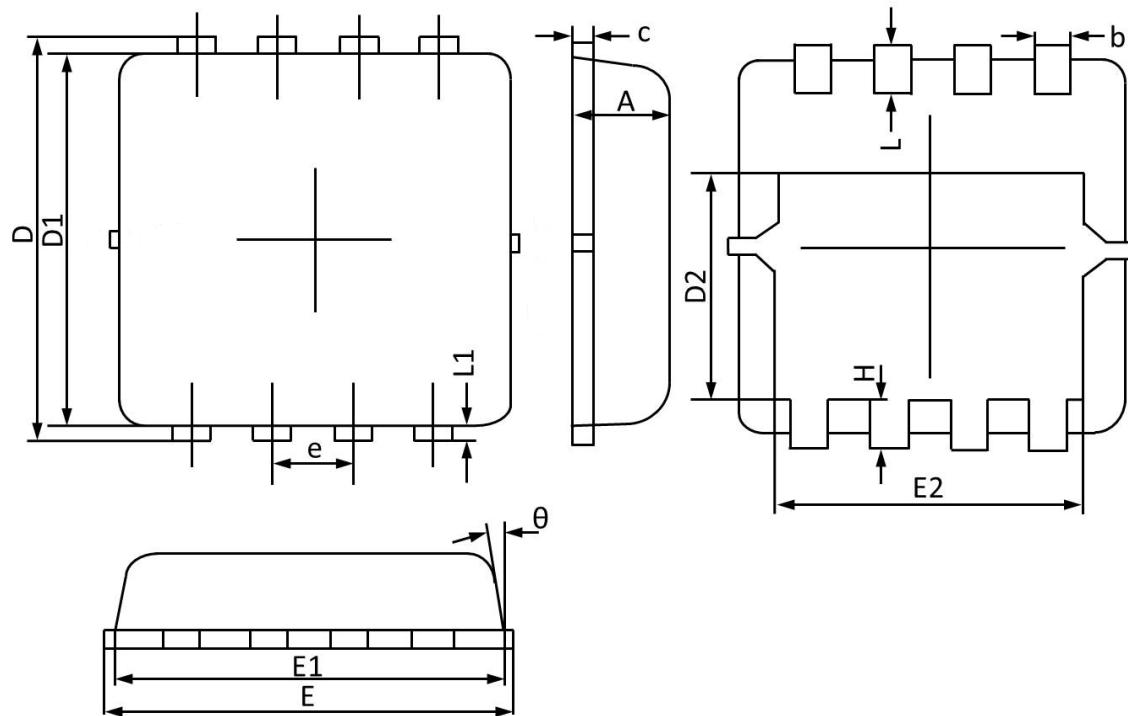

**Fig.1 Continuous Drain Current vs.  $T_C$** 

**Fig.2 Normalized RD<sub>ON</sub> vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


 V<sub>DS</sub>, Drain to Source Voltage

**Fig.7 Typical Output Characteristics**

 I<sub>D</sub>, Drain Current (A)

**Fig.8 RDSON vs. Drain Current**

**Fig.9 Switching Time Waveform**

**Fig.10 Gate Charge Waveform**

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°